



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPS70R2K0CE	Issued	25. June 2021
MA#	MA005558716		
Package	PG-TO251-3-343	Weight*	339.50 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.525	0.45	0.45	4491	4491
leadframe	inorganic material	phosphorus	7723-14-0	0.055	0.02		163	
	non noble metal	iron	7439-89-6	0.185	0.05		545	
	non noble metal	copper	7440-50-8	184.668	54.40	54.47	543939	544647
wire	non noble metal	aluminium	7429-90-5	0.515	0.15	0.15	1517	1517
encapsulation	organic material	carbon black	1333-86-4	0.730	0.21		2149	
	plastics	epoxy resin	-	19.700	5.80		58027	
	inorganic material	silicondioxide	60676-86-0	125.498	36.97	42.98	369655	429831
leadfinish	non noble metal	tin	7440-31-5	4.771	1.41	1.41	14052	14052
solder	non noble metal	tin	7440-31-5	0.037	0.01		109	
	noble metal	silver	7440-22-4	0.046	0.01		137	
	non noble metal	lead	7439-92-1	1.771	0.52	0.54	5216	5462
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com